ON Semiconductor®

Initial Product/Process Change Notification

Document #:IPCN23322X
Issue Date:29 May 2020

Title of Change:	SOIC8 Assembly Transfer of the NB3U1548CDG and NB3U1548CDR2G from SPEL to OSPI
Proposed First Ship date:	31 Jan 2021 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Eric.Rupnow@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	Affected products will be identified with date code from new assembly site.
Change Category:	Assembly Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
ON Semiconductor Carmona, Philippines	SPEL Semiconductor Limited

Description and Purpose:

Transfer assembly and test from SPEL to OSPI which includes change in Leadframe design, die attach material, mold material and bond wire diameter.

	Before Change Description	**After Change Description**
LeadFrame	SOIC8 95X130 Cu	SOIC8 256 U/S LEADFRAME
Die Attach	CRM1076NS	Ablestik ABP 8062T
Bond Wire	0.8 mil Au	1.0 mil Au
Mold Compound	G633	G700LS
Assembly Site	SPEL	OSPI Carmona

No package dimension change and no product performance change.

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Qualification Plan:

QV DEVICE NAME: **NB3U1548CDG**
RMS: **TBD**
PACKAGE: **SOIC8**

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta= 125°C, 120% nominal Vcc	1008 hrs
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
UHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	
SD	JSTD002B	Ta = 245C, 10 sec	

Estimated date for qualification completion: 14 August 2020

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

Part Number	Qualification Vehicle
NB3U1548CDG	N/A
NB3U1548CDR2G	N/A

Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NB3U1548CDG				